

WHAT IS CLAIMED IS

1. A housing preform comprised of a bendable plate member inside of which is formed electronic components and interconnects for electrically connecting said electronic components.

2. A housing preform as set forth in claim 1, wherein said plate member is comprised of a flexible substrate and a flexible protective film burying and covering said electronic components.

3. A housing preform as set forth in claim 1, wherein parts of said plate member scheduled to be bent are provided with reinforcements for preventing breakage of said interconnects.

4. A housing preform as set forth in claim 1, wherein said interconnects are formed by conductive paste.

5. A housing preform as set forth in claim 1, wherein said plate member is of the shape of the housing unfolded flat.

6. An electronic apparatus having a 3D housing comprised of a bent housing preform as set forth in any of claims 1 to 5.

7. An electronic apparatus comprised of a combination of a housing preform as set forth in any of claims 1 to 5 and system components.